

AMENDMENTS TO THE CLAIMS

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

Listing of Claims:

Claims 1-14 (Cancelled)

15. (Currently Amended) A method of making optical elements on a wafer level comprising:

making a master including a plurality of optical elements on a substantially planar surface thereof;

simultaneously imprinting a replica of said plurality of optical elements in a material by applying the substantially planar surface of the master to the imprintable material;

providing a support substrate for the replica, the support substrate having first and second opposing parallel surfaces, the replica being on one of the first and second opposing parallel surfaces;

hardening the imprintable material to form a hardened replica;

removing the master from the hardened replica;

removing imprintable material in a periphery of each of the plurality of optical elements;

and

separating the support substrate through the first and second opposing parallel surfaces in the periphery of each of the plurality of optical elements to form individual optical elements, each individual optical element including the hardened replica and the support substrate.

16. (Previously Presented) The method as recited in claim 15, further comprising providing imprintable material in a thin film on the substantially planar surface of the master prior to the imprinting.

17. (Previously Presented) The method as recited in claim 15, wherein imprinting includes:

providing the imprintable material to the substantially planar surface of the master;

providing an adhesion promoter on the support substrate; and
contacting the substantially planar surface of the master having the imprintable material thereon to a surface of the substrate having the adhesion promoter thereon.

18. (Previously Presented) The method as recited in claim 15, wherein the support substrate includes fiducial marks, the method further comprising aligning the master to the fiducial marks.

19. (Previously Presented) The method as recited in claim 15, further comprising coating the replica with an anti-reflective coating.

20. (Previously Presented) The method according to claim 15, further comprising selectively removing or adding to the optical element in a predetermined pattern.

21. (Previously Presented) The method according to claim 15, further comprising selectively removing or adding to the support substrate before imprinting.

22. (Previously Presented) The method according to claim 20, wherein selectively removing or adding occurs after imprinting.

23. (Previously Presented) The method according to claim 20, wherein selectively removing or adding includes providing metal pads on another of the first and second opposing parallel surfaces opposite where the replica is to be located.

24. (Previously Presented) The method as recited in claim 15, wherein imprinting includes imprinting both sides of the support substrate, such that a plurality of pairs of opposing, corresponding optical elements are formed on the support substrate, each individual optical element including a pair of opposing, corresponding optical elements.

25. (Previously Presented) The method as recited in claim 24, wherein a different master is used for imprinting either side of said both sides.

26. (Previously Presented) The method as recited in claim 25, wherein a first master includes diffractive optical elements and a second master includes refractive optical elements.

27. (Previously Presented) The method as recited in claim 41, further comprising providing fiducial marks on both the wafer master and the support substrate.

28. (Previously Presented) The method according to claim 41, further comprising: confirming alignment of the support substrate and the wafer master in a mask aligner; and tacking together the support substrate and wafer master at discrete locations once alignment is confirmed.

29. (Previously Presented) The method according to claim 28, further comprising removing the support substrate and the wafer master from the mask aligner after said tacking and then hardening the imprintable material.

30. (Previously Presented) The method according to claim 15, wherein said imprinting includes initially bringing the master into contact with only a portion of the support substrate, with the imprintable material on at least one of the master and the support substrate, and then bringing the entire master into contact with the support substrate with the imprintable material therebetween.

31-40. (Cancelled).

41. (Original) The method as recited in claim 15, wherein said master is a wafer.

42. (Original) The method as recited in claim 20, wherein said selectively removing or adding is lithographic.

43. (Previously Presented) The method as recited in claim 20, wherein said selectively removing or adding includes selectively removing imprintable material.

44. (Previously Presented) The method as recited in claim 43, wherein said selectively removing imprintable material includes providing metal in a pattern on said master and, after said embossing, removing away unfixed imprintable material.

45. (Previously Presented) The method as recited in claim 43, wherein said selectively removing or adding includes adding material where imprintable material was removed.

46. (Previously Presented) The method as recited in claim 28, wherein said tacking includes providing localized fixing of said imprintable material.

47-50. (Cancelled).

51. (Previously Presented) The method according to claim 15, wherein said imprinting includes initially bringing a portion of the substantially planar surface of the master into contact with a center of the support substrate, with the imprintable material on at least one of the master and the support substrate, and then bringing the entire substantially planar surface of the master into contact with the support substrate with the imprintable material therebetween.

52. (Previously Presented) The method according to claim 15, wherein said imprinting includes initially bringing a portion of the substantially planar surface of the master into contact with an edge of the support substrate, with the imprintable material on at least one of the master and the support substrate, and then bringing the entire substantially planar surface of the master into contact with the support substrate with the imprintable material therebetween.

53. – 60. (Cancelled).

61. (Previously Presented) The method according to claim 15, wherein the hardened replica is adhered to the support substrate sufficiently to avoid delamination therefrom during said separating.

62. (Previously Presented) The method according to claim 16, wherein said imprintable material covers the plurality of optical elements, providing a substantially smooth upper surface on the substantially planar surface of the master.

63.-64. (Cancelled).

65. (Previously Presented) The method as recited in claim 15, further comprising lithographically creating a plurality of optical lithographs on another of the first and second opposing parallel surfaces opposite where the replica is to be located, one of the optical lithograph and the replica being a diffractive optical element and another being a refractive optical element.

66. (Previously Presented) The method as recited in claim 65, wherein each individual optical element includes a corresponding optical lithograph.

67. (Previously Presented) The method as recited in claim 15, further comprising: lithographically creating a plurality of optical lithographs on another substrate; and securing the substrate having the replicas and the another substrate having the optical lithographs thereon before separating, one of the optical lithograph and the replica being a diffractive optical element and another being a refractive optical element.

68. (Previously Presented) The method as recited in claim 67, wherein each individual optical element includes a corresponding optical lithograph.

69. (Previously Presented) The method as recited in claim 67, wherein securing occurs at substantially planar regions of the substrates.

70. (Previously Presented) The method as recited in claim 67, wherein securing includes providing a separation mechanism between the substrates.